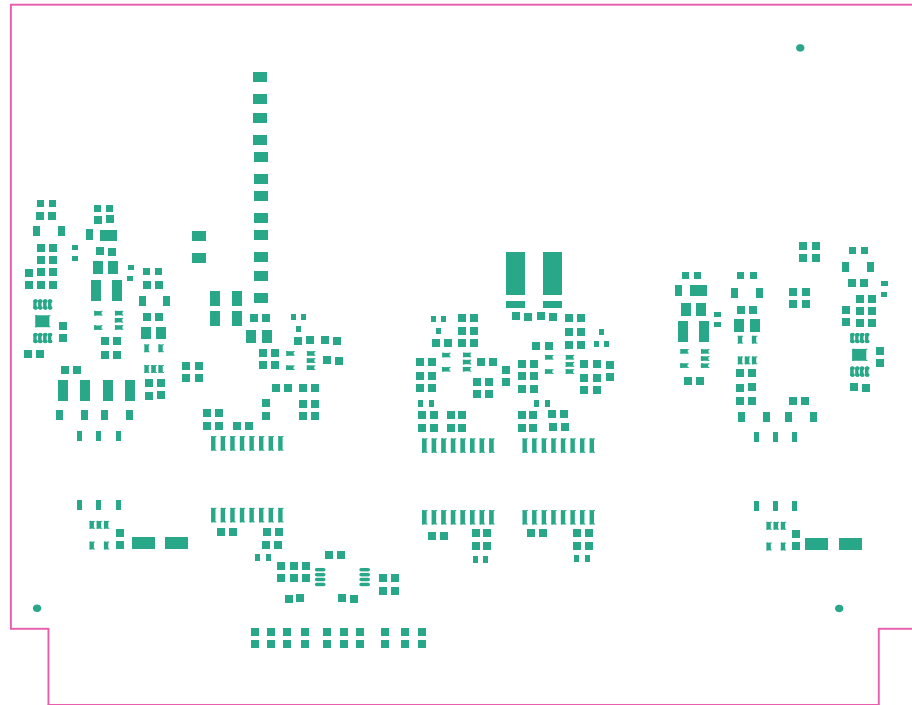
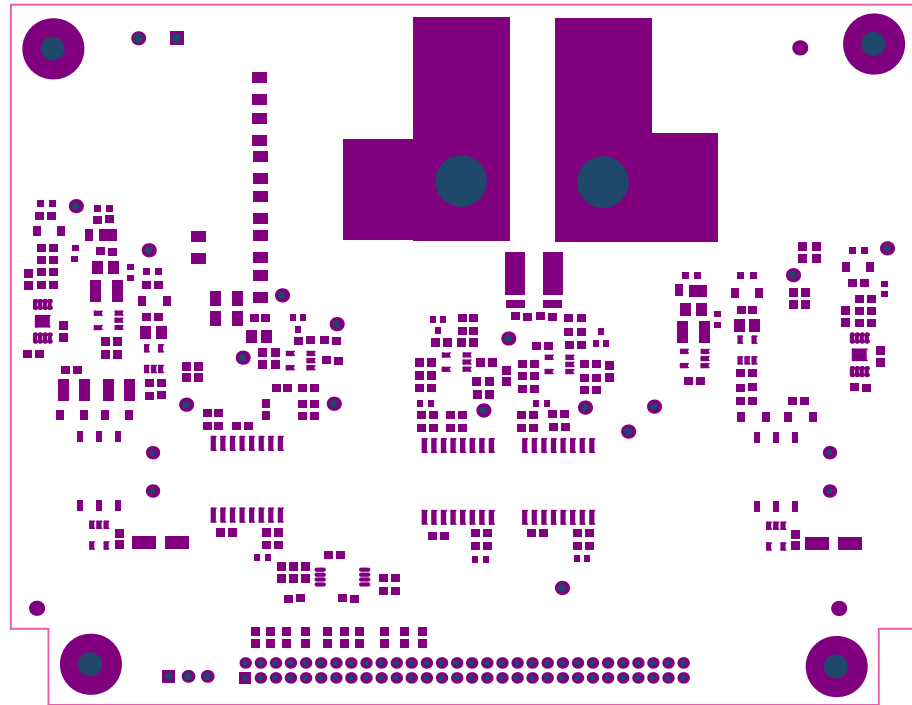


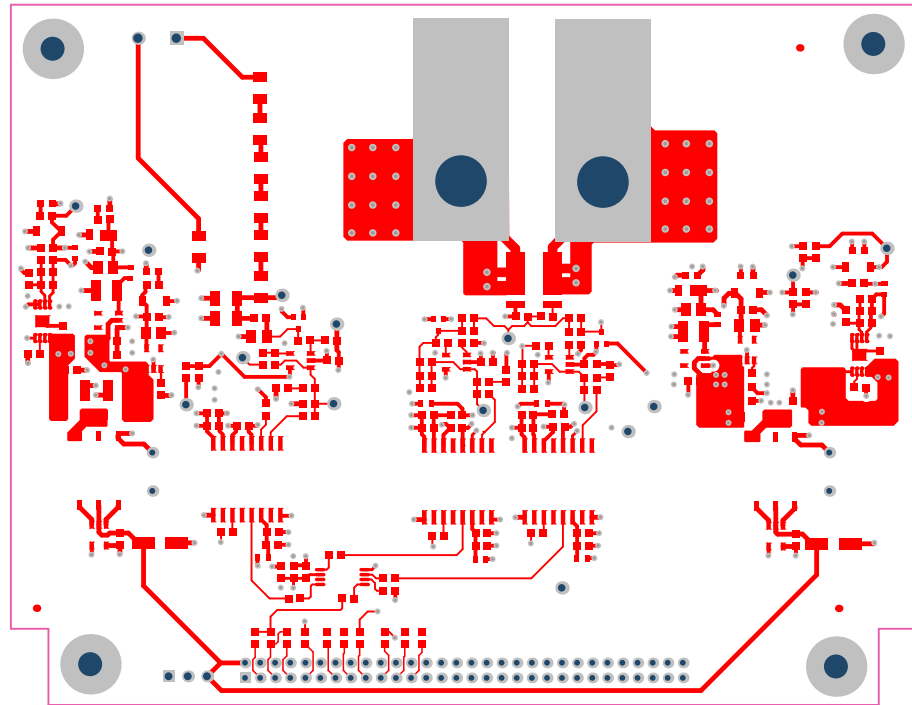
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00738_Type1	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 12/8/2015 1:03:35 PM	TEXAS INSTRUMENTS	



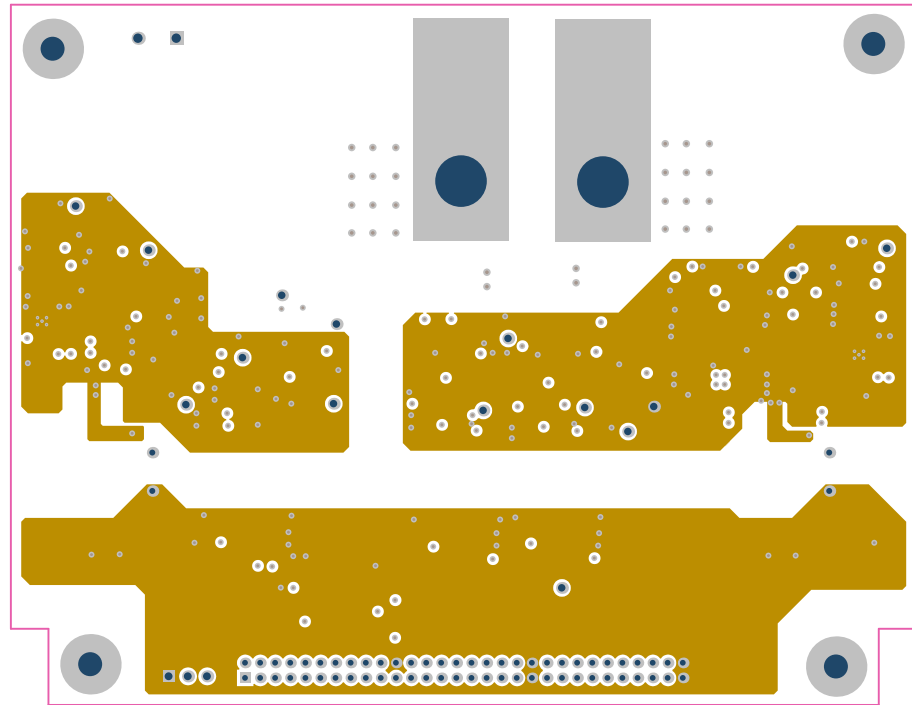
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00738_Type1	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Top Paste			
PLOT NAME = Top Paste	GENERATED : 12/8/2015 1:03:36 PM	TEXAS INSTRUMENTS	



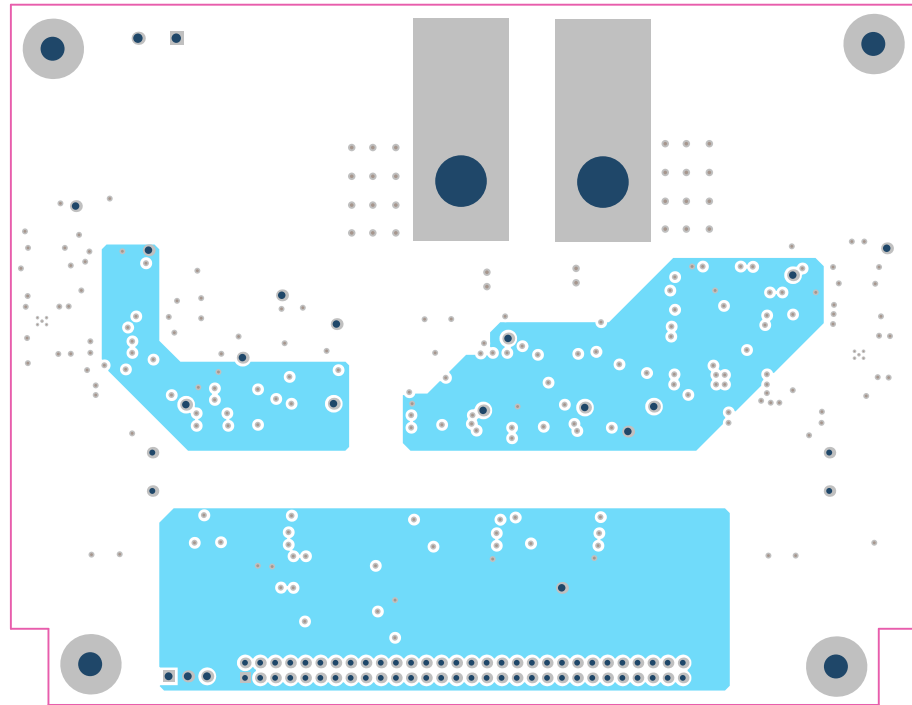
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00738_Type1	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 12/8/2015 1:03:36 PM	TEXAS INSTRUMENTS	



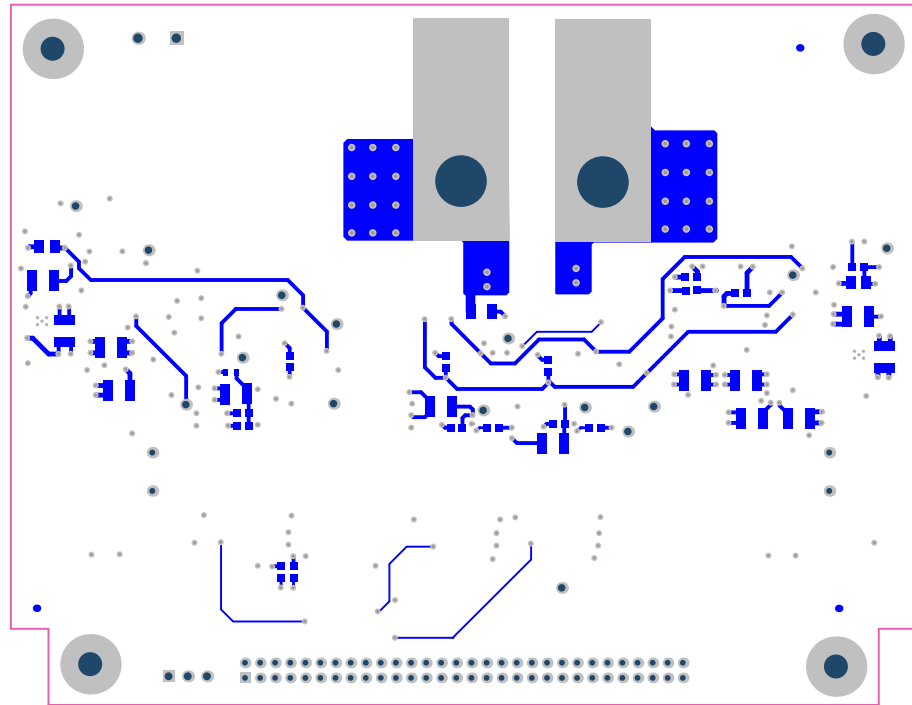
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00738_Type1	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 12/8/2015 1:03:37 PM	TEXAS INSTRUMENTS	



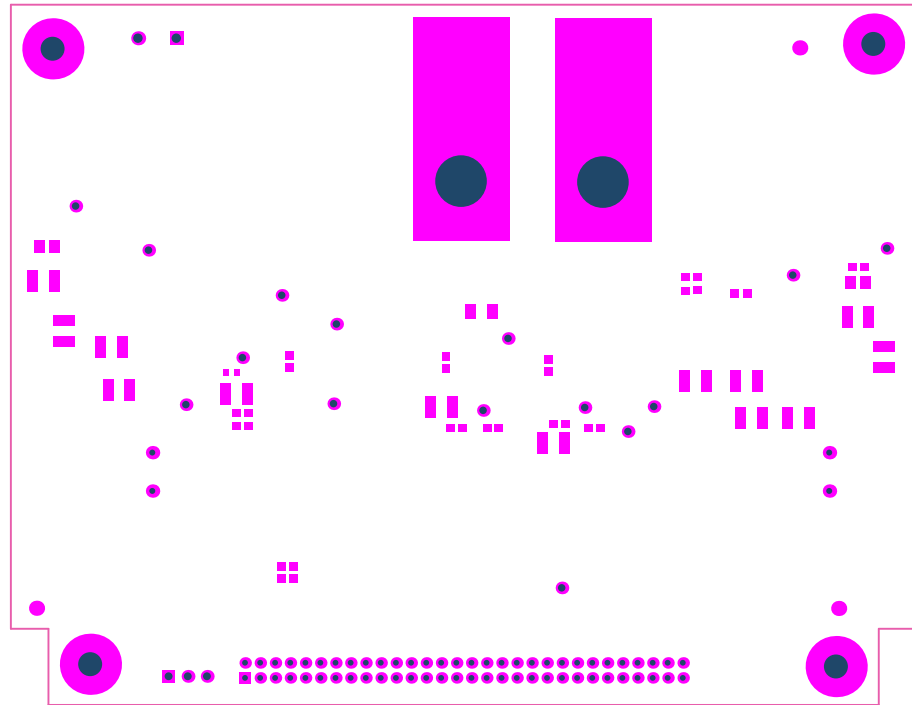
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00738_Type1	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = GND			
PLOT NAME = GND	GENERATED : 12/8/2015 1:03:37 PM	TEXAS INSTRUMENTS	



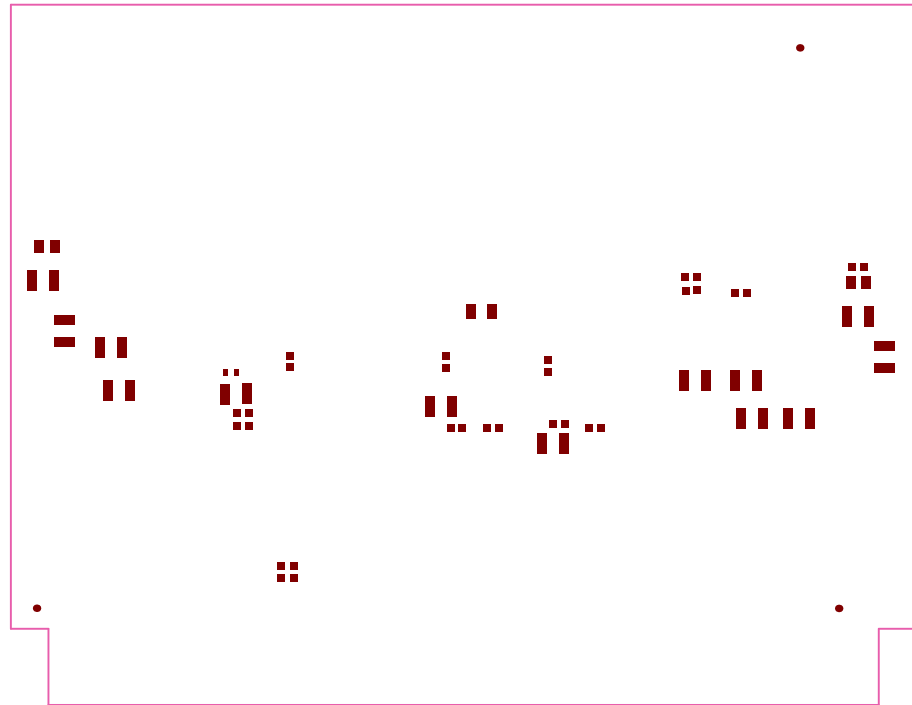
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00738_Type1	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = PWR			
PLOT NAME = PWR	GENERATED : 12/8/2015 1:03:38 PM	TEXAS INSTRUMENTS	



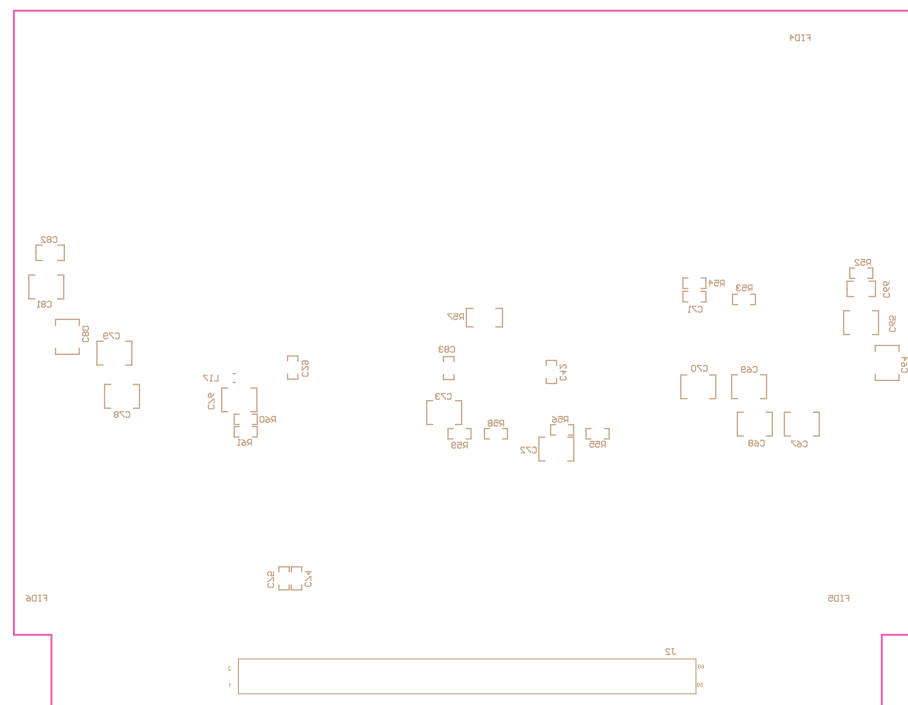
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00738_Type1	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 12/8/2015 1:03:39 PM	TEXAS INSTRUMENTS	



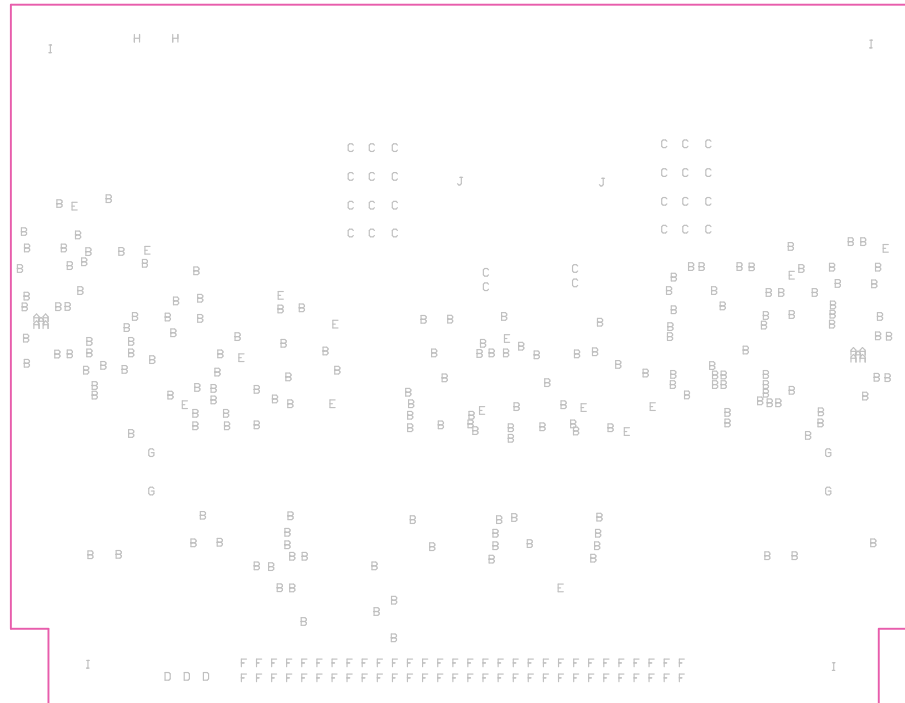
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00738_Type1	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 12/8/2015 1:03:39 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00738_Type1	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = Bottom Paste			
PLOT NAME = Bottom paste	GENERATED : 12/8/2015 1:03:39 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00738_Type1	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 12/8/2015 1:03:40 PM	TEXAS INSTRUMENTS	

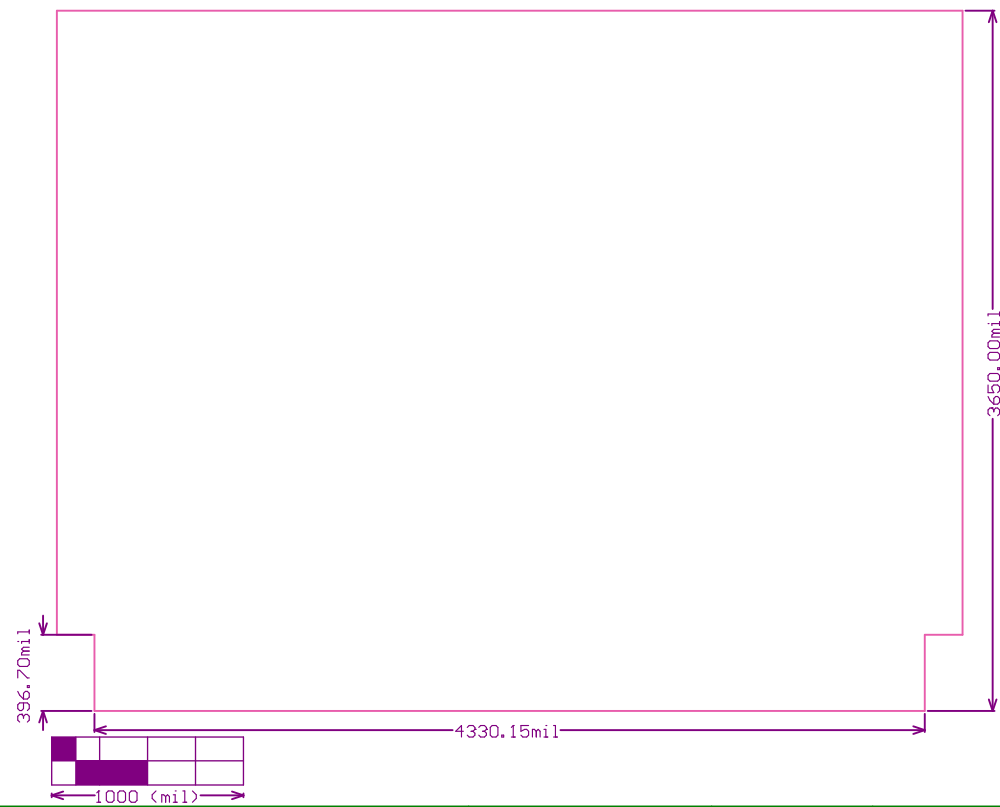


Symbol	Hit Count	Tool Size	Plated	Hole Type
A	10	7.874mil (0.2mm)	PTH	Round
B	183	16mil (0.406mm)	PTH	Round
C	28	20mil (0.508mm)	PTH	Round
F	60	31mil (0.787mm)	PTH	Round
G	4	32mil (0.813mm)	PTH	Round
E	15	40mil (1.016mm)	PTH	Round
D	3	42.126mil (1.07mm)	PTH	Round
H	2	49.213mil (1.25mm)	PTH	Round
I	4	125.984mil (3.2mm)	PTH	Round
J	2	270mil (6.858mm)	PTH	Round
	311 Total			

Drill Table

FOR 7.874MIL DRILL +/-7.874MIL
 FOR 16MIL DRILL +/-16MIL
 FOR PTH DRILL +/-3MIL

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00738_Type1	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 12/8/2015	1:03:41 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00738_Type1	REV: E2	SVN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Board Dimensions	GENERATED : 12/8/2015 1:03:42 PM	TEXAS INSTRUMENTS	

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